

T-Head Zhenwu 810E

Zhenwu

2026

OVERVIEW

— FP32 TFLOPS	96 GB Memory HBM2e	2.7 TB/s Memory Bandwidth	— TDP
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PERFORMANCE METRICS

Precision	Peak (dense)	Bits	Type
FP64	—	—	Standard
FP32	—	—	Standard
TF32	—	—	Standard
BF16	—	—	Standard
FP16	—	—	Standard
FP8	—	—	Standard
FP6	—	—	Standard
FP4	—	—	Standard
INT8	—	—	Standard

MEMORY SPECIFICATIONS

Capacity	96 GB
Type	HBM2e
Bandwidth	2.7 TB/s
Interface Width	—

POWER & EFFICIENCY

TDP	—
Max power	—
FP32 dense TFLOPS per W of TDP	—
FP16 dense TFLOPS per W of TDP	—
Per W of TDP figures divide dense peak by accelerator TDP. Board power only: excludes host CPUs, networking, cooling and facility overhead.	

HARDWARE DETAILS

Vendor: T-Head	Architecture: Zhenwu	Process Node: —
Form Factor: —	Launch Year: 2026	

INTERCONNECT

GPU-to-GPU: ICN	Bandwidth: 700 GB/s direction and scope not stated by vendor	Links: 7
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